Dual 4-Stage Binary Ripple Counter with + 2 and + 5 **Sections**

High-Performance Silicon-Gate CMOS

The MC74HC390A is identical in pinout to the LS390. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of two independent 4-bit counters, each composed of a divide-by-two and a divide-by-five section. The divide-by-two and divide-by-five counters have separate clock inputs, and can be cascaded to implement various combinations of $\div 2$ and/or \div 5 up to a \div 100 counter.

Flip-flops internal to the counters are triggered by high-to-low transitions of the clock input. A separate, asynchronous reset is provided for each 4-bit counter. State changes of the O outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and should not be used as clocks or strobes except when gated with the Clock of the HC390A.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No 7 A
- Chip Complexity: 244 FETs or 61 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

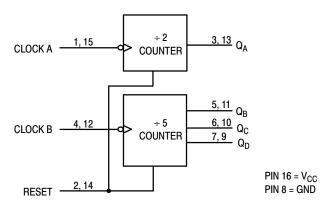


Figure 1. Logic Diagram



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SOIC-16 **D SUFFIX** CASE 751B

DT SUFFIX CASE 948F

PIN ASSIGNMENT

CLOCK A _a [1 ●	16	□ v _{cc}
RESET a	2	15	CLOCK A _b
Q _{Aa} [3	14	RESET b
CLOCK B _a [4	13	Q _{Ab}
Q _{Ba} [5	12	CLOCK B _b
Q _{Ca} [6	11] Q _{Bb}
Q _{Da} [7	10] Q _{Cb}
GND [8	9	Q _{Db}
			•

MARKING DIAGRAMS





TSSOP-16

SOIC-16

= Assembly Location L, WL = Wafer Lot Y, YY = Year

W, WW = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

Clo	ock		
Α	В	Reset	Action
Х	Х	Н	Reset ÷ 2 and ÷ 5
_	Х	L	Increment ÷ 2
Х	~	L	Increment ÷ 5

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
l _{in}	DC Input Current, per Pin	±20	mA
l _{out}	DC Output Current, per Pin	±25	mA
Icc	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating: SOIC Package: -7 mW/°C from 65° to 125°C TSSOP Package: -6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)		6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)		V _{CC}	V
T _A	Operating Temperature, All Package Types	-55	+125	°C
t _r , t _f	Input Rise and Fall Time $V_{CC} = 2.0$ (Figure 1) $V_{CC} = 3.0$ $V_{CC} = 4.0$ $V_{CC} = 6.0$	V 0 V 0	1000 600 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V _{CC} V	–55 to 25°C	≤85°C	≤125°C	Unit
V _{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V _{IL}	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V _{OH}	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH} \text{ or } V_{IL} \qquad I_{out} \le 2.4 \text{ mA} \\ I_{out} \le 4.0 \text{ mA} \\ I_{out} \le 5.2 \text{ mA}$	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V _{OL}	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$\begin{split} V_{in} = V_{IH} \text{ or } V_{IL} & I_{out} \leq 2.4 \text{ mA} \\ I_{out} \leq 4.0 \text{ mA} \\ I_{out} \leq 5.2 \text{ mA} \end{split}$	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND) (continued)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V _{CC}	–55 to 25°C	≤85°C	≤125°C	Unit
l _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	4	40	160	μΑ

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_f = t_f = 6 ns)

			Gu	aranteed Li	mit	
Symbol	Parameter	v _{cc}	–55 to 25°C	≤85°C	≤125°C	Unit
f _{max}	Maximum Clock Frequency (50% Duty Cycle)	2.0	10	9	8	MHz
	(Figures 1 and 3)	3.0	15	14	12	
		4.5	30	28	25	
		6.0	50	45	40	
t _{PLH} ,	Maximum Propagation Delay, Clock A to QA	2.0	70	80	90	ns
t _{PHL}	(Figures 1 and 3)	3.0	40	45	50	
		4.5	24	30	36	
		6.0	20	26	31	
t _{PLH} ,	Maximum Propagation Delay, Clock A to QC	2.0	200	250	300	ns
t _{PHL}	(QA connected to Clock B)	3.0	160	185	210	
	(Figures 1 and 3)	4.5	58	65	70	
		6.0	49	62	68	
t _{PLH} ,	Maximum Propagation Delay, Clock B to QB	2.0	70	80	90	ns
t _{PHL}	(Figures 1 and 3)	3.0	40	45	50	
		4.5	26	33	39	
		6.0	22	28	33	
t _{PLH} ,	Maximum Propagation Delay, Clock B to QC	2.0	90	105	180	ns
t _{PHL}	(Figures 1 and 3)	3.0	56	70	100	
		4.5	37	46	56	
		6.0	31	39	48	
t _{PLH} ,	Maximum Propagation Delay, Clock B to QD	2.0	70	80	90	ns
t _{PHL}	(Figures 1 and 3)	3.0	40	45	50	
		4.5	26	33	39	
		6.0	22	28	33	
t _{PHL}	Maximum Propagation Delay, Reset to any Q	2.0	80	95	110	ns
	(Figures 2 and 3)	3.0	48	65	75	
		4.5	30	38	44	
		6.0	26	33	39	
t _{TLH} ,	Maximum Output Transition Time, Any Output	2.0	75	95	110	ns
t _{THL}	(Figures 1 and 3)	3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	15	19	
C _{in}	Maximum Input Capacitance	_	10	10	10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Counter)*	35	pF

^{*} Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

TIMING REQUIREMENTS (Input $t_r = t_f = 6 \text{ ns}$)

			Gu	aranteed Li	mit	
Symbol	Parameter	V _{CC}	–55 to 25°C	≤85°C	≤125°C	Unit
t _{rec}	Minimum Recovery Time, Reset Inactive to Clock A or Clock B (Figure 3)	2.0 3.0 4.5 6.0	25 15 10 9	30 20 13 11	40 30 15 13	ns
t _w	Minimum Pulse Width, Clock A, Clock B (Figure 2)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 15	110 36 22 19	ns
t _w	Minimum Pulse Width, Reset (Figure 3)	2.0 3.0 4.5 6.0	75 27 20 18	95 32 24 22	110 36 30 28	ns
t _f , t _f	Maximum Input Rise and Fall Times (Figure 2)	2.0 3.0 4.5 6.0	1000 800 500 400	1000 800 500 400	1000 800 500 400	ns

PIN DESCRIPTIONS

INPUTS Clock A (Pins 1, 15) and Clock B (Pins 4, 15)

Clock A is the clock input to the \div 2 counter; Clock B is the clock input to the \div 5 counter. The internal flip-flops are toggled by high-to-low transitions of the clock input.

CONTROL INPUTS Reset (Pins 2, 14)

Asynchronous reset. A high at the Reset input prevents counting, resets the internal flip–flops, and forces $Q_{\rm A}$ through $Q_{\rm D}$ low.

OUTPUTS Q_A (Pins 3, 13)

Output of the \div 2 counter.

Q_B, Q_C, Q_D (Pins 5, 6, 7, 9, 10, 11)

Outputs of the \div 5 counter. Q_D is the most significant bit. Q_A is the least significant bit when the counter is connected for BCD output as in Figure 5. Q_B is the least significant bit when the counter is operating in the bi–quinary mode as in Figure 6.

SWITCHING WAVEFORMS

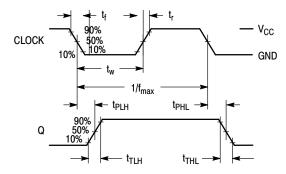


Figure 2.

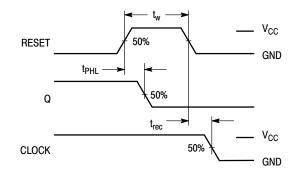
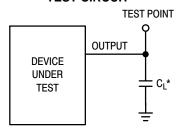


Figure 3.

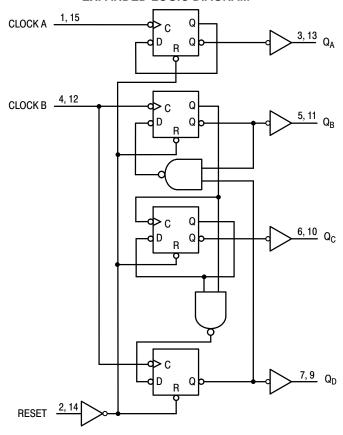
TEST CIRCUIT



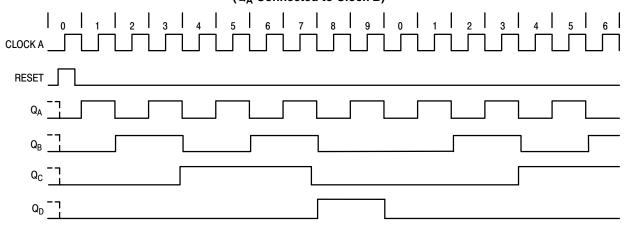
*Includes all probe and jig capacitance

Figure 4.

EXPANDED LOGIC DIAGRAM



TIMING DIAGRAM (Q_A Connected to Clock B)



APPLICATIONS INFORMATION

Each half of the MC54/74HC390A has independent \div 2 and \div 5 sections (except for the Reset function). The \div 2 and \div 5 counters can be connected to give BCD or bi–quinary (2–5) count sequences. If Output Q_A is connected to the Clock B input (Figure 4), a decade divider with BCD output is obtained. The function table for the BCD count sequence is given in Table 1.

To obtain a bi–quinary count sequence, the input signals connected to the Clock B input, and output Q_D is connected to the Clock A input (Figure 6). Q_A provides a 50% duty cycle output. The bi–quinary count sequence function table is given in Table 2.

Table 1. BCD Count Sequence*

		Output				
Count	Q_D	Q _C	Q _B	Q_A		
0	L	L	L	L		
1	L	L	L	Н		
2	L	L	Н	L		
3	L	L	Н	Н		
4	L	Н	L	L		
5	L	Н	L	Н		
6	L	Н	Н	L		
7	L	Н	Н	Н		
8	Н	L	L	L		
9	Н	L	L	Н		

^{*}QA connected to Clock B input.

Table 2. Bi-Quinary Count Sequence**

	Output				
Count	Q_A	Q_D	Q _C	Q _B	
0	L	L	L	L	
1	L	L	L	Н	
2	L	L	Н	L	
3	L	L	Н	Н	
4	L	Н	L	L	
8	Н	L	L	L	
9	Н	L	L	Н	
10	Н	L	Н	L	
11	Н	L	Н	Н	
12	Н	Н	L	L	

^{**} QD connected to Clock A input.

CONNECTION DIAGRAMS

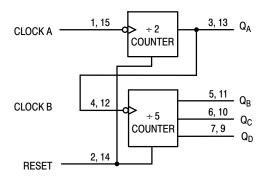


Figure 5. BCD Count

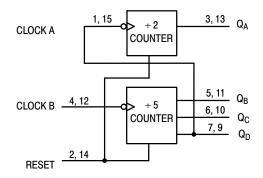


Figure 6. Bi-Quinary Count

ORDERING INFORMATION

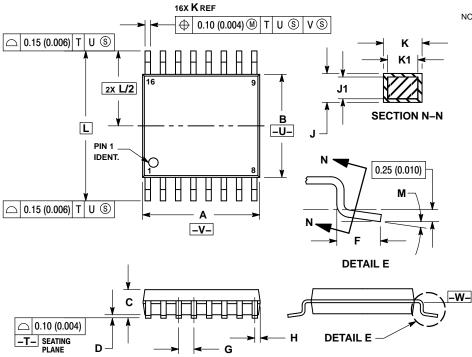
Device	Package	Shipping [†]
MC74HC390ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC390ADR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC74HC390ADTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
NLV74HC390ADR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

PACKAGE DIMENSIONS

TSSOP-16 CASE 948F **ISSUE B**



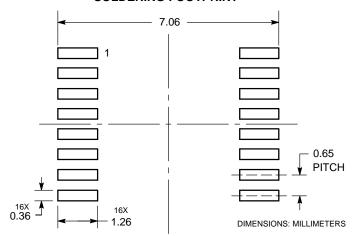
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
 - FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE
 INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
 MOLE EXCEED A 26 (2010) PER DIPT
 - NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR

 - 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0°	8°	0°	8 °

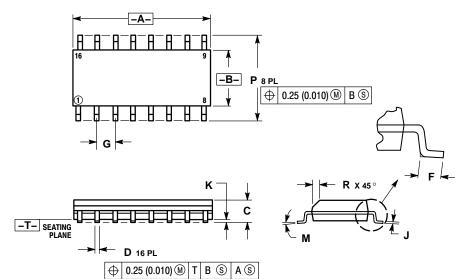
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOIC-16 CASE 751B-05 ISSUE K

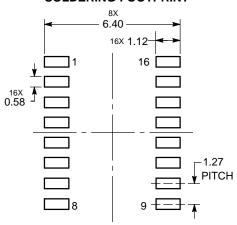


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27 BSC		0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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